

BGAE240 | eMMC | 153-ball/100-ball

SMART's BGAE240 eMMC is an embedded memory solution that combines NAND Flash memory, an embedded MMC (MultiMediaCard) controller, and advanced firmware in a small BGA (Ball Grid Array) package that provides stable, yet cost effective high-density embedded storage.

SMART's BGAE240 eMMC solution is available in the standard JEDEC 0.5mm pitch, 153-ball package, as well as an eMMC interposer module which has a footprint and pin-out compatible with the JEDEC Standard 1.0mm pitch, 100-ball package. The 100-ball package offers a solution with large ball pitch and ball diameter which enables lower cost PCB designs, simplifies PCB routing with wider metal traces, resulting in better thermal dissipation.

Wide Temp

(-40°C to +105°C)





Features & Benefits

- Compliant to JEDEC v5.0 Standard
- Capacities from 4GB to 32GB
- Pre-Configurable to pSLC Enhanced Storage Media Mode
- Wide Temp (-40°C to +105°C)
- VCC = 3.3V and VCCQ = 3.3V or 1.8V

Applications

- Factory Automation
- Medical Devices
- Networking Appliances
- POS Terminals
- RFID Scanners
- Single-Board Computers
- VolP

Product Family Overview

Form Factor	Capacity	Sequential Performance
BGAE240 (MLC)	8GB to 32GB	Up to 540MB/s Read
BGAE240 (pSLC)	4GB to 16GB	Up to 460MB/s Write

Specifications (BGAE240 MLC)

	BGAE240 MLC 100-ball MLC	
NAND Type		
Performance		
Host Interface Rate (maximum)	eMMC v5.0 (HS400)	
Capacities	8GB to 32GB	
Sequential Read (maximum)	Up to 260 MB/s	
Sequential Write (maximum)	Up to 130 MB/s	
Random Read (maximum)	Up to 6000 IOPS	
Random Write (maximum)	Up to 2200 IOPS	
Reliability		
Endurance	32GB: 56 TBW	
Endurance (Sequential Workload)	16GB: 24 TBW	
	8GB: 10 TBW	
Data Retention	10 years	
Error Correction	ВСН	
Power		
Input Voltage	3.3V ± 10%	
Environmental		
On anating Charle	1500 g half-sine, 0.5 msec, 1 shock along each axis,	
Operating Shock	X, Y, Z in each direction	
Operating Vibration	20G 80-2000Hz, 1.52mm 20-80Hz, 3 axis	
Operating Temperature	Wide: -40°C to +105°C	
Storage Temperature	-40°C to +105°C	
Physical		
Length	14 mm	
Width	18 mm	
Height	2.45 mm	

Ordering Information (BGAE240 MLC)

Part Number	Density			
BGAE240 MLC eMMC 100-ball Wide Operating Temperature (-40°C to +105°C)				
SPQBGP1CWW01	32GB			
SPQAGP1CWW01	16GB			
SPQ8GP1CWW01	8GB			

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Specifications (BGAE240 pSLC)

	BGAE240 pSLC 153-ball	BGAE240 pSLC 100-ball
NAND Type	pSLC	
Performance		
Host Interface Rate (maximum)	eMMC v5.0 (HS400)	
Capacities	4GB to 16GB	
Sequential Read (maximum)	Up to 260 MB/s	
Sequential Write (maximum)	Up to 160 MB/s	
Random Read (maximum)	Up to 5500 IOPS	
Random Write (maximum)	Up to 2200 IOPS	
Reliability		
Endurance	16GB: 215 TBW	
	8GB: 91 TBW	
(Sequential Workload)	4GB: 35 TBW	
Data Retention	10 years	
Error Correction	ВСН	
Power		
Input Voltage	3.3V ± 10%	
Environmental		
On anothing Objects	1500 g half-sine, 0.5 msec, 1 shock along each axis,	
Operating Shock	X, Y, Z in each direction	
Operating Vibration	20G 80-2000Hz, 1.52mm 20-80Hz, 3 axis	
Operating Temperature	Wide: -40°C to +105°C	
Storage Temperature	-40°C to +105°C	
Physical		
Length	11.5 mm	14 mm
Width	13 mm	18 mm
Height	1 mm	2.45 mm

Ordering Information (BGAE240 pSLC)

Part Number	Density		
BGAE240 pSLC eMMC 153-ball Wide Operating Temperature (-40°C to +105°C)			
SPMBGP1CWW11	16GB		
SPMAGP1CWW11	8GB		
SPM8GP1CWW11	4GB		
BGAE240 pSLC eMMC 100-ball Wide Operating Temperature (-40°C to +105°C)			
SPQBGP1CWW11	16GB		
SPQAGP1CWW11	8GB		
SPQ8GP1CWW11	4GB		



For more information, please visit: www.smartm.com

*Product images are for promotional purposes only. Labels may not be representative of the actual product.

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